



#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on) max</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
-40V	11mΩ @ V <sub>GS</sub> = -10V	-10.1A
	15mΩ @ V <sub>GS</sub> = -4.5V	-8.8A

# Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power management functions
- Analog Switch

### **Features and Benefits**

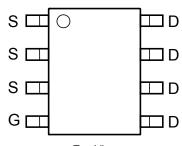
- 100% Unclamped Inductive Switch (UIS) test in production
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

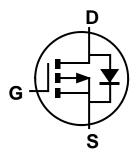
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0072 grams (approximate)







Top View Internal Schematic



Equivalent circuit

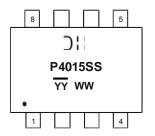
#### Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
DMP4015SSS-13	Commercial	SO-8	2,500/Tape & Reel
DMP4015SSSQ-13	Automotive	SO-8	2,500/Tape & Reel

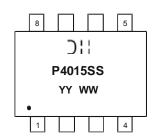
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

### **Marking Information**



Chengdu A/T Site



Shanghai A/T Site

⊃¦¦ = Manufacturer's Marking
 P4015SS = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 13 = 2013)
 WW = Week (01 - 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	-40	V		
Gate-Source Voltage		_	$V_{GSS}$	±25	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-9.1 -7.2	Α
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-7.8 -6.2	Α
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-10.1 -8.0	Α
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-8.8 -7.0	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-100	Α		
Avalanche Current (Note 7)	I <sub>AS</sub>	-22	Α		
Avalanche Energy (Note 7)	Eas	242	mJ		

### **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_{D}$	1.45	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	88	°C/W
Total Power Dissipation (Note 6)	$P_{D}$	1.82	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	70	°C/W
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta Jc}$	7.6	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C

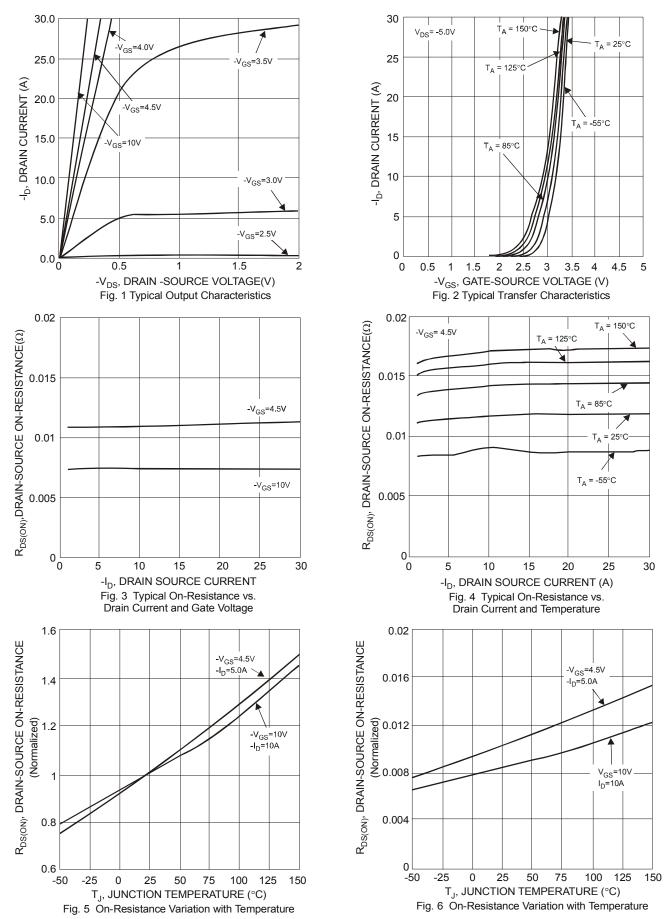
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	$BV_{DSS}$	-40		_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	-1	μA	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>			±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	$V_{GS(th)}$	-1.5	-2.0	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	D		7	11	mΩ	$V_{GS} = -10V, I_D = -9.8A$	
Static Dialii-Source Off-Resistance	R <sub>DS</sub> (ON)		9	15	11122	$V_{GS} = -4.5V$ , $I_D = -9.8A$	
Forward Transfer Admittance	Y <sub>fs</sub>		26	_	S	$V_{DS} = -20V, I_{D} = -9.8A$	
Diode Forward Voltage (Note 5)	$V_{SD}$		-0.7	-1.0	<b>V</b>	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>		4234			), oo, , , , , , , , , , , , , , , , , ,	
Output Capacitance	Coss		1036		pF	$V_{DS} = -20V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		526	_		1 = 1.0WH12	
Gate Resistance	$R_G$		7.77		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg		47.5		00)/ // 5)/		
Gate-Source Charge	$Q_{gs}$	_	14.2	_	nC	$V_{DS} = -20V, V_{GS} = -5V$ $I_{D} = -9.8A$	
Gate-Drain Charge	$Q_{gd}$	_	13.5	_			
Turn-On Delay Time	t <sub>D(on)</sub>	_	13.2	_		$V_{GS} = -10V, V_{DD} = -20V, R_G = 6\Omega,$	
Turn-On Rise Time	t <sub>r</sub>	1	10.0		20		
Turn-Off Delay Time	t <sub>D(off)</sub>	_	302.7	_	ns	$I_D = -1A, R_L = 20\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	1	137.9	_			

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate
- 7. UIS in production with L = 1mH, T<sub>J</sub> = +25°C
  8. Short duration pulse test used to minimize self-heating effect.
  9. Guaranteed by design. Not subject to production testing.







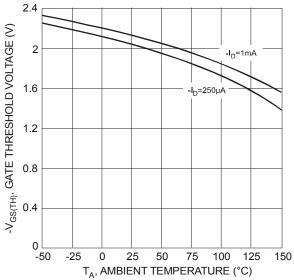
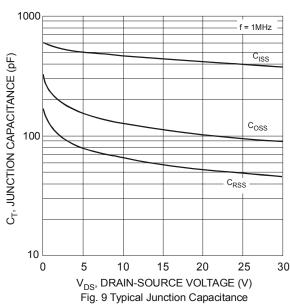
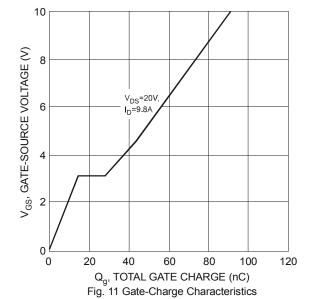
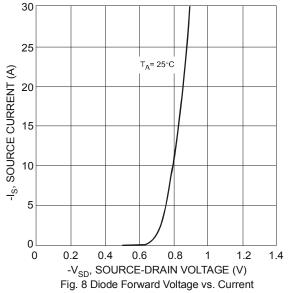


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







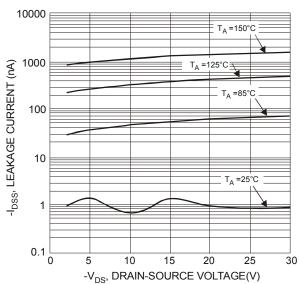
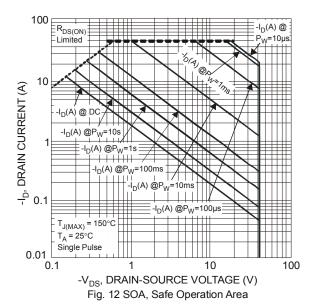


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage





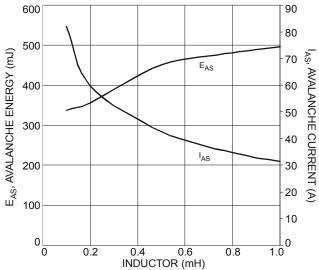
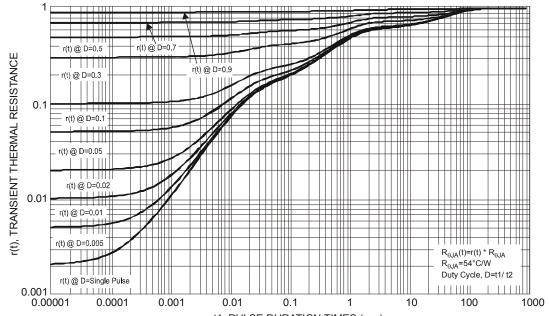


Fig. 13 Single-Pulse Avalanche Tested

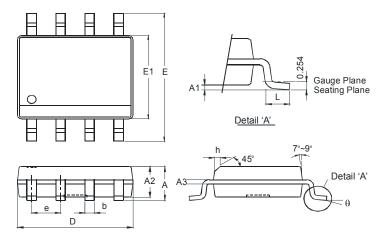


t1, PULSE DURATION TIMES (sec) Fig. 14 Transient Thermal Resistance



### **Package Outline Dimensions**

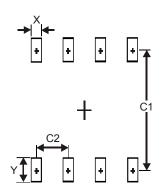
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8				
Dim	Min	Max		
Α	-	1.75		
<b>A</b> 1	0.10	0.20		
A2	1.30	1.50		
А3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85 3.95			
е	1.27 Typ			
h	1	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27



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